

**Corrected Claim Set:**

1. (Previously Presented) A leadframe comprising:  
a plurality of leads, each lead comprising a first surface, an opposite second surface, an inner end segment which defines an inner end of the lead, and an outer portion extending from the inner end segment,  
wherein a first subset of the leads each include a recess in the first surface of the lead at the inner end segment, a second subset of the leads each include a recess in the second surface of the lead at the inner end segment, and the individual leads of the first subset are situated in an alternating lateral pattern with the individual leads of the second subset such that the recesses in the inner end segments of the leads of any pair of adjacent leads are oriented in opposite directions.
2. (Withdrawn) The leadframe of claim 1, wherein the recess in the inner end segment of the leads extends to the inner end of the respective lead.
3. (Original) The leadframe of claim 1, wherein the recess of the inner end segment of the leads of the first subset does not extend to the inner end of the lead, and the leads of the first subset extend further toward a center of the leadframe than the leads of the second subset.
4. (Previously Presented) The leadframe of claim 1, wherein the inner end of each of the leads is of a first width, and at least a portion of the outer portion of each of the leads is of a second width which is less than the first width.
5. (Cancelled)
6. (Original) The leadframe of claim 1, wherein each recess has a vertical depth that is more than half of a vertical height of the lead.
7. (Previously Presented) The leadframe of claim 1, further comprising a plurality of electrical conductors, wherein the inner end segments are respectively electrically connected to a semiconductor chip by one of said plurality of electrical conductors.
8. (Previously Presented) The leadframe of claim 7, where at least some of the plurality of electrical conductors are respectively electrically connected within the recess of the respective inner end segment.

9. (Previously Presented) A leadframe comprising:

a plurality of pairs of adjacent metal leads, wherein each lead includes an inner end segment which defines an inner end of the lead and has a recessed surface, and an outer portion extending from the inner end segment, and

wherein the recessed surfaces of the leads of each said pair of adjacent leads are spaced apart a first distance in a vertical direction, and said first distance is greater than a second distance in a horizontal direction between closest portions of the recessed surfaces of the leads of each said pair of adjacent leads.

10. (Original) The leadframe of claim 9, wherein the first distance is greater than half a vertical height of an unrecessed portion of the lead.

11. (Original) The leadframe of claim 9, wherein the second distance is approximately zero.

12. (Previously Presented) The leadframe of claim 11, wherein the second distance is zero.

13. (Withdrawn) The leadframe of claim 9, wherein the recessed surface in the inner end segments extends to the inner end of the respective lead.

14. (Previously Presented) The leadframe of claim 9, further comprising a plurality of electrical conductors, wherein the inner end segments of the leads are respectively electrically connected to a semiconductor chip by one of said plurality of electrical conductors, and at least some of said plurality of electrical conductors are connected to the recessed surface of the respective inner end segment.

15. (Original) The leadframe according to claim 9, wherein the recessed surface of one of the leads of the pairs does not extend to the inner end of the lead, and those leads extend further toward a center of the leadframe than the other respective pair.

16. (Previously Presented) The leadframe of claim 9, further comprising a dam bar connected to the outer segments of the leads.

17. (Previously Presented) A leadframe comprising:

a plurality of adjacent pairs of leads each including an inner segment which defines an inner end of the lead and has a recessed surface, and an outer portion extending from the inner segment, the recessed surfaces of the inner end segments of the leads of each of the pairs being oppositely oriented.

18. (Withdrawn) The leadframe of claim 17, wherein the recessed surface in the inner end segments extends to the inner end of the lead.

19. (Previously Presented) The leadframe of claim 17, further comprising a plurality of electrical conductors, wherein the inner end segments of the pairs of adjacent leads are respectively electrically connected to a semiconductor chip by one of said plurality of electrical conductors, and at least some of said plurality of electrical conductors are connected to the recessed surface of the respective inner end segment.

20. (Original) The leadframe of claim 17, wherein the recessed surface of one of the leads of the pairs does not extend to the inner end of the lead, and those leads extend further toward a center of the leadframe than the other lead of the respective pair.

21. (Withdrawn) The leadframe of claim 20, wherein a semiconductor chip is in a flip chip electrical connection with the inner end segments.

22. (Previously Presented) The leadframe of claim 17, wherein the inner end segment of each of the leads is of a first width, and at least a portion of the outer portion of each of the leads is of a second width which is less than the first width.

23. **(Previously Presented)** A semiconductor package comprising:

a plurality of adjacent pairs of leads each including an inner segment which defines an inner end of the lead and has a recessed surface, and an outer portion extending from the inner segment, the recessed surfaces of the inner end segments of the leads of each of the pairs being oppositely oriented;

a semiconductor chip in an electrical connection with the inner end segments of the leads; and

a hardened encapsulant material covering the semiconductor chip, and the inner end segments of the leads.

24. (Previously Presented) The semiconductor package of claim 23, wherein the electrical connection comprises a plurality of electrical connectors bonded between the semiconductor chip and the inner end segments, wherein at least some of said plurality of electrical conductors are bonded to the recessed surface of the respective inner end surface.

25. (Withdrawn) The semiconductor package of claim 23, wherein the recessed surface in the inner end segments extends to the inner end of the lead.

26. (Original) The semiconductor package of claim 23, wherein the recessed surface of one of the leads of the pairs does not extend to the inner end of the lead, and those leads extend further toward the semiconductor chip than the other lead of the respective pair.

27. (Withdrawn) The semiconductor package of claim 23, wherein the semiconductor chip is in a flip chip electrical connection with the inner end segments.

28. (Previously Presented) The semiconductor package of claim 23, wherein the inner end segment of each of the leads is of a first width, and at least a portion of the outer portion of each of the leads is of a second width which is less than the first width.

29. **(Previously Presented)** A semiconductor package comprising:

a plurality of pairs of adjacent metal leads, wherein each lead includes an inner end segment which defines an inner end of the lead and has a recessed surface, and an outer portion extending from the inner end segment, and

wherein the recessed surfaces of the leads of each said pair of adjacent leads are spaced apart a first distance in a vertical direction, and said first distance is greater than a second distance in a horizontal direction between closest portions of the recessed surfaces of the leads of each said pair of adjacent leads;

a semiconductor chip in an electrical connection with the inner end segments of the leads; and

a hardened encapsulant material covering the semiconductor chip, the conductors, and the inner end segments of the leads.

30. (Original) The semiconductor package of claim 29, wherein the first distance is greater than half a vertical height of an unrecessed portion of the lead.

31. (Original) The semiconductor package of claim 29, wherein the second distance is approximately zero.

32. (Withdrawn) The semiconductor package of claim 29, wherein the recessed surface in the inner end segments extends to the inner end of the respective lead.

33. (Original) The semiconductor package of claim 29, wherein the electrical connection comprises a plurality of metal wires bonded between the semiconductor chip and the inner end segments, wherein at least some of said wires are bonded to the recessed surface of the respective inner end segment.

34. (Original) The semiconductor package of claim 29, wherein the recessed surface of one of the leads of the pairs does not extend to the inner end of the lead, and those leads extend further toward the semiconductor chip than the other lead of the respective pair.

35. (Previously Presented) The leadframe of claim 1, wherein the inner ends of the leads of the first subset extend further toward a center of the leadframe than the inner ends of the leads of the second subset.

36. (Previously Presented) The leadframe of claim 1, where the inner end segments of the leads of the first subset include a pedestal between the inner end of the lead and the recess.

37. (Previously Presented) The leadframe of claim 36, wherein the inner ends of the leads of the first subset extend further toward a center of the leadframe than the inner ends of the leads of the second subset.

38. (Previously Presented) The leadframe of claim 1, wherein the inner end segments of the leads of the first subset include a pedestal between the inner end of the lead and the recess, and the recesses of the second subset of the leads extend to the inner end of the lead.

39. (Previously Presented) The leadframe of claim 38, wherein the inner ends of the leads of the first subset extend further toward a center of the leadframe than the inner ends of the leads of the second subset.

40. (Previously Presented) The leadframe of claim 9, wherein the inner end of one lead of each said pair extends further toward a center of the leadframe than the inner end of the other lead of the pair.

41. (Previously Presented) The leadframe of claim 9, wherein one lead of each said pair includes a pedestal between the inner end of the lead and the recessed surface, and the recessed surface of the other lead of the pair extends to the inner end of the lead.

42. (Previously Presented) The leadframe of claim 41, wherein the inner end of one lead of each said pair extends further toward a center of the leadframe than the inner end of the other lead of the pair.

43. (Previously Presented) The leadframe of claim 17, wherein the inner end of one lead of each said pair extends further toward a center of the leadframe than the inner end of the other lead of the pair.

44. (Previously Presented) The leadframe of claim 17, wherein one lead of each said pair includes a pedestal between the inner end of the lead and the recessed surface of the lead, and the recessed surface of the other lead, and the recessed surface of the other lead of the pair extends to the inner end of the lead.

45. (Previously Presented) The leadframe of claim 44, wherein the inner end of one lead of each said pair extends further toward a center of the leadframe than the inner end of the other lead of the pair.

46. (Previously Presented) The semiconductor package of claim 23, wherein the inner end of one lead of each said pair extends further toward the semiconductor chip than the inner end of the other lead of the pair.

47. (Previously Presented) The semiconductor package of claim 23, wherein one lead of each said pair includes a pedestal between the inner end of the lead and the recessed surface, and the recessed surface of the other lead of the pair extends to the inner end of the lead.

48. (Previously Presented) The semiconductor package of claim 47, wherein the inner end of one lead of each said pair extends further toward a center of the leadframe than the inner end of the other lead of the pair.

49. (Previously Presented) The semiconductor package of claim 47, wherein the electrical connection to the lead of the pair having the pedestal is located at the pedestal.

50. (Previously Presented) The semiconductor package of claim 29, wherein one lead of each said pair includes a pedestal between the inner end of the lead and the recessed surface.

51. (Previously Presented) The leadframe of claim 50, wherein the inner end of one lead of each said pair extends further toward a center of the leadframe than the inner end of the other lead of the pair.

52. (Previously Presented) The leadframe of claim 29, wherein the inner end of one lead of each said pair extends further toward a center of the leadframe than the inner end of the other lead of the pair.